



Material Content Data Sheet



Sales Product Name	BFR 183W H6327			Issued		29. August 2013		
MA#	MA000820250							
Package	PG-SOT323-3-1			Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.05		454	
	non noble metal	tin	7440-31-5	0.001	0.01		117	
	inorganic material	silicon	7440-21-3	0.016	0.26	0.32	2641	3213
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1324	
	non noble metal	copper	7440-50-8	2.617	43.95	44.13	439406	441257
wire	noble metal	gold	7440-57-5	0.007	0.12	0.12	1226	1226
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5303	
	plastics	epoxy resin	-	0.679	11.40		114023	
	inorganic material	silicondioxide	60676-86-0	2.448	41.10	53.03	411015	530342
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22281	22281
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1681	1681
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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